

XPERIA Z Ultra , C68 Faulty Boards

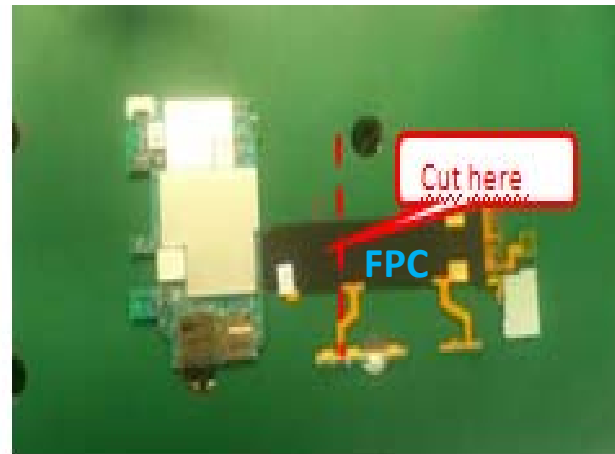
E2E Escalation Packing Instruction

Prepare Faulty Board for Packing

Below describe the steps how to prepare the faulty board packing for escalate from SL to HVC, HVC to Hub, Hub(TES-AMM or ML) to EMS.



1) The connection between the board and FPC should not be broken. Please handle with care.



2) Cut the FPC at the marker

Packing in ESD bag and Bubble bag



3) Put board into shield bag and position FPC upward



4) HVC tear label from phone and paste on the shielding bag(optional)



5) Insert shield bag with board into bubble bag



6) **Make sure FPC must be position upwards when put into slot to prevent damage**



7) HVC print E2E label from E2E system and paste outside the bubble bag

Master Box with slot dividers



8) Remove dividers to make space for boards



9) One slot can contain up to 2 boards



10) Put the bubble bag into the all slot of the carton box and ready to ship to hub by DHL.